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Mani Adich

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application for:

Steven Teig, et al.

Serial No.: 10/066,094

Filing Date: 1/31/02

For: CIRCULAR VIAS AND  
INTERCONNECT-LINE  
TERMINATIONS

Examiner: <not assigned yet>

FILED  
MAY 29 2003  
FBI 600 MAIL ROOM

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Please amend the application as follows:

**IN THE SPECIFICATION**

Please delete the "Claim of Benefit to Provisional Application" on page 1, lines 2-9, and insert therein a new "Claim of Benefit to Prior Applications" as follows:

**-CLAIM OF BENEFIT TO PROVISIONAL APPLICATION**

This patent application claims the benefit of the earlier-field U.S. Provisional Patent Application entitled "Interconnect Method, Apparatus, and Architecture for Integrated Circuits and Integrated-Circuit Layouts", having serial number 60/295,735, and filed 6/3/2001; and U.S. Provisional Patent Application entitled "Interconnect Method, Apparatus, and Architecture for Integrated Circuits and Integrated-Circuit Layouts", having serial number 60/298,146, and filed